

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	29	("20010000684" "20040250989" "20050201063" "20050276021" "20060056154" "20060139891" "4825337" "5680295" "5161087" "5966287" "6130820" "6278610" "6707673" "6775139" "6888719" "6119765" "6188576" "6233150" "6266244" "6424532" "6466441" "6535387" "7187552" "7312996" "7349219" "7349220" "7365985" "7400506" "7403383").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 16:55
S2	1397	361/697.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 16:59
S3	0	S2 ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:00
S4	0	361/704.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:00
S5	0	361/715-716.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:00
S6	1	361/719.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:00

S7	0	361/717.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:00
S8	0	361/729.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:00
S9	0	361/748.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:01
S10	0	165/80.3.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:01
S11	0	165/185.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:01
S12	0	439/485.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:01
S13	0	439/487.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:01
S14	1	257/675.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:01
S15	9	"361"/\$.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:01
S16	1	"165"/\$.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:02
S17	32	"257"/\$.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:02
S18	2	"439"/\$.ccls. ((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:03

S19	712	((power or semiconductor) (tilt with plate) heat\$3 memory)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:03
S20	78	S19 (memory near2 (unit or modul\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:03
S21	53	S20 cool\$3	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:03
S22	43	S21 (pivot\$4 or rotat \$4)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:04
S23	37	S22 ((heat or cool) near2 (sink or plate))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:04
S24	0	S23 (((heat or cool) near2 (sink or plate)) with (tilt or pivot\$4 or rotat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:05
S25	58	"361"/\$.ccls. ((RAM or (memory near2 (modul \$3 or unit))) (((heat or cool) near2 (sink or plate)) with (tilt or pivot \$4 or rotat\$4)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/28 17:05
S26	11	("20030026076" "20050276021" "5109318" "5815371" "5966287" "6119765" "6233150" "6535387" "7079396" "7221569").PN. OR ("7349220").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/28 17:24
S27	0	(10/776680).APP.	USPAT; USOCR	AND	ON	2009/04/29 09:31
S28	7	("5161087" "5764482" "6088228" "6188576").PN. OR ("6278610").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 09:53

S29	29	"4858070" "4916575" "5594204" "5596486" "5608610" "5657203" "5671122" "5703754" "5731633").PN. OR ("6188576").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 09:54
S30	269	"361"/\$.ccls. ((DIMM or RAM OR SIP or (memory near "2" (unit or modul\$3))) ((heat or cool) near2 (sink or plate)) (axis or hinge))	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 10:04
S31	240	S30 (PCB or board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/29 10:12
S32	81	S31 (plug or insert)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/29 10:12
S33	58	"165"/\$.ccls. ((SIMM OR DIMM or RAM OR SIP or (memory near "2" (unit or modul\$3))) ((chip or IC or semiconductor or memory) with (heat or cool)) ((sink or plate or cool\$3 or body or dissipat\$3) with (axis or hinge)))	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 10:19
S34	103	"257"/\$.ccls. ((SIMM OR DIMM or RAM OR SIP or (memory near "2" (unit or modul\$3))) ((chip or IC or semiconductor or memory) with (heat or cool)) ((sink or plate or cool\$3 or body or dissipat\$3) with (axis or hinge)))	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 10:30

S35	90	"361"/\$.cds. ((SIMM OR DIMM or RAM OR SIP or (memory near "2" (unit or modul\$3))) ((chip or IC or semiconductor or memory) with (heat or cool)) ((sink or plate or cool\$3 or body or dissipat\$3) with (axis or hinge)))	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 10:43
S36	0	((SIMM OR DIMM or RAM OR SIP or (memory near "2" (unit or modul\$3))) ((chip or IC or semiconductor or memory) with (heat or cool)) ((sink or plate or cool\$3 or body or dissipat\$3) with (axis or hinge)))	EPO; JPO; DERWENT	AND	ON	2009/04/29 10:44
S37	623	((SIMM OR DIMM or RAM OR SIP or (memory near "2" (unit or modul\$3))) ((chip or IC or semiconductor or memory) with (heat or cool)) ((sink or plate or cool\$3 or body or dissipat\$3) with (axis or hinge)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:00
S38	443	S37 ((chip or IC or semiconductor or memory) with (sink or plate or cool\$3 or body or dissipat\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:04
S39	337	S38 ((heat or cool) near4 (sink or plate or cool\$3 or body or dissipat\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:04
S40	1	S39 ((insert or plug) with (SIMM OR DIMM or RAM OR SIP or (memory near "2" (unit or modul\$3))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:06

S41	17	"361"/\$.ccls. ((board or PCB or substrate) strip ((insert or plug) with (SIMM OR DIMM or RAM OR SIP or (memory near "2" (unit or modul\$3))))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:07
S42	120	"361"/\$.ccls. ((board or PCB or substrate) ((insert or plug) with (SIMM OR DIMM or RAM OR SIP or (memory near "2" (unit or modul\$3))))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:10
S43	46	S42 (heat or cool)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:10
S44	18889	((heat or cool) near3 (sink or plate or body)) (SIMM OR DIMM or RAM OR DRAM OR SIP or ((semiconductor or memory) near2 (unit or modul\$3))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:15
S45	9180	S44 ((PCB or board or substrate) contact)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:15
S46	1943	S45 ((tilt or axis or pivot\$4 or rotat\$4) with (sink or plate or body))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:17
S47	552	S46 hinge	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:17
S48	44	S47 ("361"/\$.ccls. or "165"/\$.ccls. or "174"/\$.ccls. or "257"/\$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:20
S49	0	"174"".16.""3".ccls. (((heat or cool) near3 (sink or plate or body)) (SIMM OR DIMM or RAM OR DRAM OR SIP or ((semiconductor or memory) near2 (unit or modul\$3))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:22

S50	150	174/16.3.ccls.(((heat or cool) near3 (sink or plate or body)) (SIMM OR DIMM or RAM OR DRAM OR SIP or ((semiconductor or memory) near2 (unit or modul\$3))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:23
S51	109	S50 ((PCB or board or substrate) contact)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:23
S52	22	S51 ((tilt or axis or pivot\$4 or rotat\$4) with (sink or plate or body))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:24
S53	614	"174"/\$.ccls.(((heat or cool) near3 (sink or plate or body)) (SIMM OR DIMM or RAM OR DRAM OR SIP or ((semiconductor or memory) near2 (unit or modul\$3))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:30
S54	129	S53 (plug or insert)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/29 11:30
S55	112	S54 contact	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/29 11:30
S56	9	S55 hinge	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/29 11:30
S57	12	"361"/\$.ccls. ((memory near2 (strip or modul \$3)) ((insert or plug) with (PCB or board or substrate or strip)) ((tilt or axis or pivot\$4 or rotat\$4 or hinge) with (sink or plate or body)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:32

S58	7	"257"/\$.ccls. ((memory near2 (strip or modul\$3)) ((insert or plug) with (PCB or board or substrate or strip)) ((tilt or axis or pivot\$4 or rotat\$4 or hinge) with (sink or plate or body)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:33
S59	3	"165"/\$.ccls. ((memory near2 (strip or modul\$3)) ((insert or plug) with (PCB or board or substrate or strip)) ((tilt or axis or pivot\$4 or rotat\$4 or hinge) with (sink or plate or body)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:33
S60	2	"174"/\$.ccls. ((memory near2 (strip or modul\$3)) ((insert or plug) with (PCB or board or substrate or strip)) ((tilt or axis or pivot\$4 or rotat\$4 or hinge) with (sink or plate or body)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:34
S61	100	((memory near2 (strip or modul\$3)) ((insert or plug) with (PCB or board or substrate or strip)) ((tilt or axis or pivot\$4 or rotat\$4 or hinge) with (sink or plate or body)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:34
S62	89	S61 contact	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:35
S63	13	((cool near2 plate) (memory near2 module)) ("361"/\$.ccls or "165"/\$.ccls. or "174"/\$.ccls. or "257"/\$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 11:47

S64	11	("20030026076" "20050276021" "5109318" "5815371" "5966287" "6119765" "6233150" "6535387" "7079396" "7221569").PN. OR ("7349220").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 11:52
S65	20	"5966287"	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 12:18
S66	1	"5966287".pn.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 12:18
S67	0	(10/776680).APP.	USPAT; USOCR	AND	ON	2009/04/29 12:30
S68	37	foxconn.as. (memory near2 module)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 12:53
S69	15	("20030026076" "20070195489" "20070206359" "20070217160" "3506877" "5109318" "5966287" "6119765" "6233150" "6297966" "6765797" "7221569" "7349220" "7375964").PN. OR ("7457122").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 13:13
S70	11	("20030026076" "20050276021" "5109318" "5815371" "5966287" "6119765" "6233150" "6535387" "7079396" "7221569").PN. OR ("7349220").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 13:16
S71	4967	((memory or semiconductor or chip or IC) near2 module) ((heat or cool or dissipat\$3) with (sink or plate or body))) ("361"/\$.ccls or "165"/ \$.ccls. or "174"/\$.ccls. or "257"/\$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 13:24

S72	61	S71 ((pivot\$4 or rotat \$4 or tilt) with (join\$4 or axis or hinge) with (sink or plate or body))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2009/04/29 13:26
S73	7	("5161087" "5764482" "6088228" "6188576").PN. OR ("6278610").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 13:27
S74	1	"7215551".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/29 14:25
S75	2	US "20060067054"	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/04/29 14:26
S76	7	("20060056160" "6535387" "6775139" "7023700" "7079396").PN. OR ("7312996").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 14:35
S77	18	("20070139897" "3893161" "4872505" "5109318" "5513135" "5784263" "5901781" "6173382" "6208517" "6278610" "6424532" "6507912" "6510100" "6535387" "7079396" "7106595" "7312996" "7403383").PN. OR ("7474529").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 14:36
S78	18	("20040161953" "20070053170" "20070064401" "20070121286" "4935845" "5410448" "5528455" "6198629" "6285548" "6512672" "6738262" "6744632" "6785142" "6920050" "7092252" "7269006" "7280356").PN. OR ("7403383").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 14:36

S79	15	("20030026076" "20070195489" "20070206359" "20070217160" "3506877" "5109318" "5966287" "6119765" "6233150" "6297966" "6765797" "7221569" "7349220" "7375964").PN. OR ("7457122").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 14:38
S80	24	("3187087" "3798506" "4027206" "4625260" "4707726" "5208729" "5228192" "5276584" "5370517" "5567986" "5684675" "5719745" "5751553" "5757073" "5779134" "5808417" "5831847" "6000132" "6020661" "6201695" "6319756" "6449161").PN. OR ("6707673").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/04/29 15:39

4/ 29/ 2009 5:35:42 PM

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